Model JFP PP7 SERIES

FLIP CHIP & FLEXIBLE REWORK STATION

Bond Head

Removal Module & Live Video

Flip Mixed Video Alignment

Pick & Place
Flip Chip assembly
Very small and large component
Reflow, thermal cycle
Eutectic thermo cycle
Wafer sorter up to 8"
Local reflow using hot gas gun
Integrated shear force removal device
Solder bumps removal
Glue residues cleaning & leveling
Live inspection video

Dual Chambers Eutectic Oven

The JFP PP7 is a complete solution semi automatic Flip-Chip and flexible rework platform. It can be used in a wide field of applications. It achieves maximum accuracy placement using high quality optical device. Flip feature will allow a perfect alignment of parts and substrate, mixing both video pictures with a placement @< 3 μm @ 3 sigma. A robust, and reliable mechanical concept, designed to be external vibration free. The PP7 is user friendly, flexible and requires minimal training to operate.
Specifications

| Model: | Flip Chip Die Bonder PP7  
|       | Pick & Place regular device  
|       | Pick & Place flipped device  
| Motorized Tables: | X 250mm, Y 100mm / 1µm  
|       | Micro metric Manual Theta adjustment  
|       | Joystick control: 2 speeds, adjustable  
| Pick & Place Head | Motorized Z  
|       | Vacuum picking tool, 1/8  
|       | Minimum force: 10gr  
| Die size: | Minimum 150*150 µm  
|       | Minimum 25mm*25mm  
| Substrate handled: | Up to 300x500 mm  
| Flip chip: | Up-looking camera  
|       | Dual vision computing system  
| Vision: | Dual CCD Color camera  
|       | 17” TFT panel  
|       | Up-looking camera  
|       | Dual video mixer for simultaneous alignment  
|       | Target Crosshair generator  
| Rework | BGA & Flip chip with solder removal module  
| Oven | Double chamber eutectic workholder Max Temp 450C  
| Live video | Camera live video fully integrated in user interface  
| Alignment: | Place Mode direct for flip application  
|       | 2 Ref point / Indexed XY at P&P position  
| Parameters: | Friendly Graphic user interface  
|       | Force: 10gr to 6 Kg programmable  
|       | Bond Time: 1ms to 10sec programmable  
|       | US Power: up to 30W programmable  
|       | Scrub: XY amplitude and cycle programmable  
| Matrix: | Mapping / step and repeat / 2 ref point / Indexed  
| PC System | Stable software architecture  
| Utilities | 100Vac to 230Vac / 500W  
|       | Vacuum: 70%  

Options
- Eutectic Digital temperature profile control. 3 set points with enclosure double chamber workholder
- Heated Work-Holder up to 8 inches (200mm)
- Double micro jet hot gas
- Ultrasonic Flip High Power digital ultrasonic generator & 60KHz heavy duty transducer
- Oven C4 compatible
- Heavy duty bond head, 3 ranges Programmable up to 15Kg
- Piezo driven micro gripper pick up head
- Dispenser
- Stamping
- UV insulator